



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-09-21
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CSVX*BX09T6F	A	Z8GA	2015-09-21
Amount	UoM	Unit type	ST ECOPACK Grade	
8.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	210	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.9X1.625X1.175	3	gull wing	
Comment	Package: SOT 23; MDF valid for STR2550			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name		CSVX*BX09T6F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	0.434	mg	supplier	die	Silicon (Si)	7440-21-3		0.413	mg	951613	51625	
Die				supplier	metallization	Aluminum (Al)	7429-90-5		0.013	mg	29954	1625	
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	16129	875	
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	2304	125	
Leadframe	Copper & its alloys	3.507	mg	supplier	alloy	Copper (Cu)	7440-50-8		3.333	mg	950385	416625	
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.08	mg	22812	10000	
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.003	mg	855	375	
Leadframe				supplier	alloy	Zinc(Zn)	7440-66-6		0.005	mg	1426	625	
Leadframe				supplier	metallization	Silver(Ag)	7440-22-4		0.086	mg	24522	10750	
Die attach	Other organic materials	0.111	mg	supplier	Glue	Silver(Ag)	7440-22-4		0.087	mg	783784	10875	
Die attach				supplier	Glue	isobornyl Methacrylate	7534-94-3		0.016	mg	144144	2000	
Die attach				supplier	Glue	Bismaleimide resin	Proprietary		0.004	mg	36036	500	
Die attach				supplier	Glue	polymer	Proprietary		0.004	mg	36036	500	
Bonding wire	Other inorganic materials	0.012	mg	supplier	Bonding wire	Copper(CU)	7440-50-8		0.012	mg	1000000	1500	
encapsulation	Other inorganic materials	3.826	mg	supplier	mold compound	Epoxy Resin	Proprietary		0.287	mg	75013	35875	
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		0.191	mg	49922	23875	
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		3.313	mg	865917	414125	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.019	mg	4966	2375	
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.016	mg	4182	2000	
connections coating	Solder	0.11	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.11	mg	1000000	13750	